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(54) **ELECTRONIC DEVICE**

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(57) **ABSTRACT**

Embodiments of this application provide an electronic device, which solves the problem of mutual influence between a heat dissipation component and a patch antenna in the electronic device by multiplexing a heat sink in the electronic device. The heat sink provided by the embodiments of this application can be used as a heat dissipation component to distribute heat evenly, so as to achieve the purpose of cooling down an overheated electronic element. In addition, the heat sink can be used as a radiator of an antenna to form an antenna unit with the feed unit and generate radiation to the outside. The heat sink in a first region can be used as a main radiator of the antenna unit to meet the demand for the number of antennas in a 5G wireless communication system, and can also be applied to other communication systems.